

REMARKS/ARGUMENTS

The Office Action of June 24, 2005, has been carefully considered.

It is noted that claims 1-13 are rejected under 35 U.S.C. §102(b) over Japanese reference 01-296636 to Hisataka.

In view of the Examiner's rejection of the claims, applicants have amended independent claim 1.

It is respectfully submitted that the claims presently on file differ essentially and in an unobvious, highly advantageous manner from the constructions disclosed in the reference.

Turning now to the reference, it can be seen that Hisataka discloses a wire bonding device for a hybrid integrated circuit. Hisataka does not disclose a bumping/bonding site as in the presently claimed invention. In Hisataka, the bonding site is located essentially in the middle of a housing 1 through which the devices are carried during bonding. To allow the capillary to access the devices situated inside the housing 1, a work hole 17 is necessary together with a shifting cover 15 that covers the working hole 17. This is a cumbersome design since the shifting cover 15 needs to be displacement-driven as the capillary moves. In the presently claimed invention, the support table is operative to move the semiconductor devices from a bumping site into the chamber system after bumping. This solves the problem of having to accommodate the capillary inside the chamber system. In Hisataka, the wire bonding is carried out with the devices already in the middle of the housing, and thus does not anticipate claim 1.

Therefore, it is respectfully submitted that Hisataka does not disclose the features recited in the claims presently on file.

In view of these considerations, it is respectfully submitted that the rejection of claims 1-13 under 35 U.S.C. §102(b) over the above discussed reference is overcome and should be withdrawn.

Reconsideration and allowance of the present application are respectfully requested.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on September 13, 2005:

Robert C. Faber

Name of applicant, assignee or
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Signature

September 13, 2005

Date of Signature

RCF:KPS:ck

Respectfully submitted,



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